

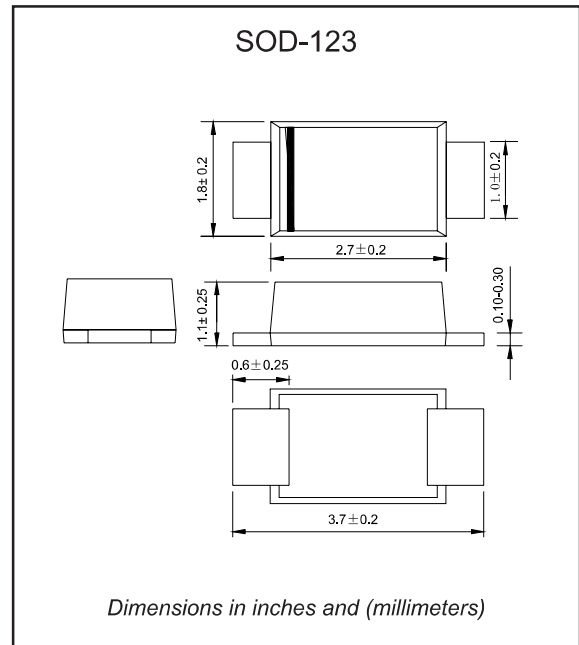
### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:  
260°C/10 seconds
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

### Mechanical data

- ◆ **Case**: JEDEC SOD-123 molded plastic body
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any

### Package outline

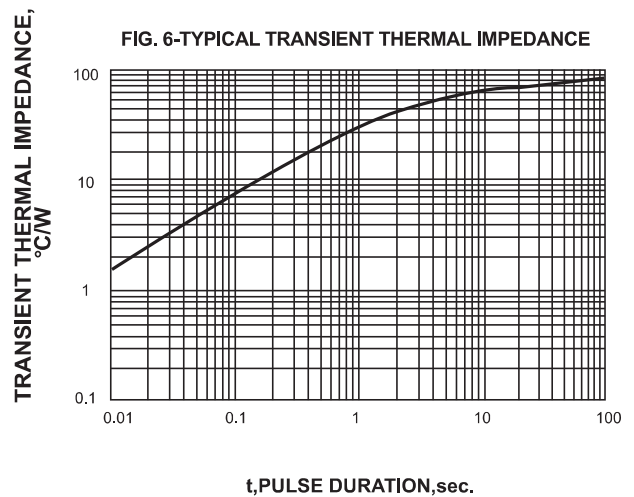
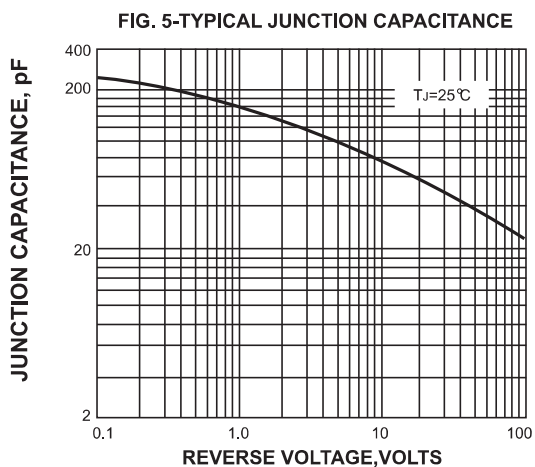
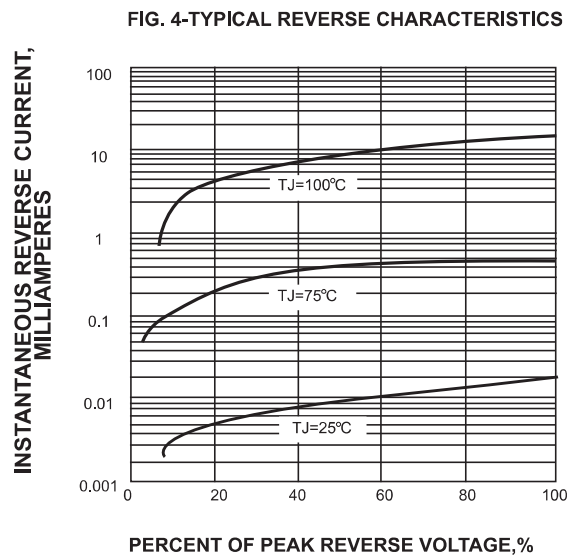
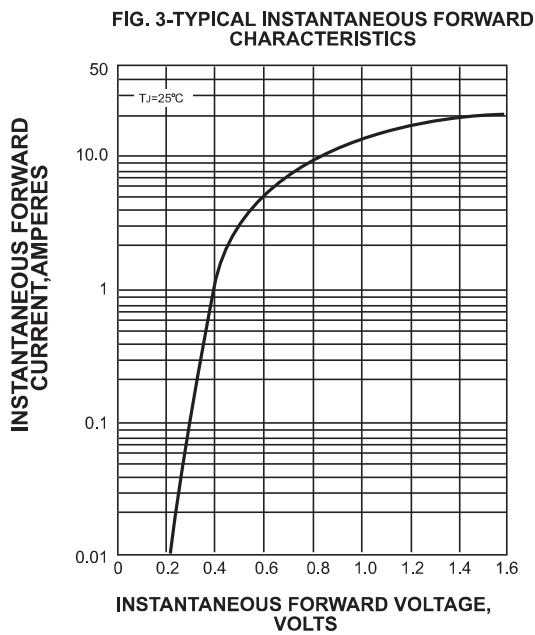
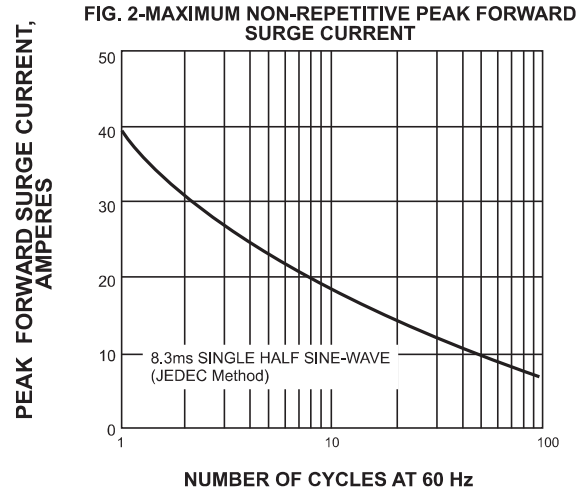
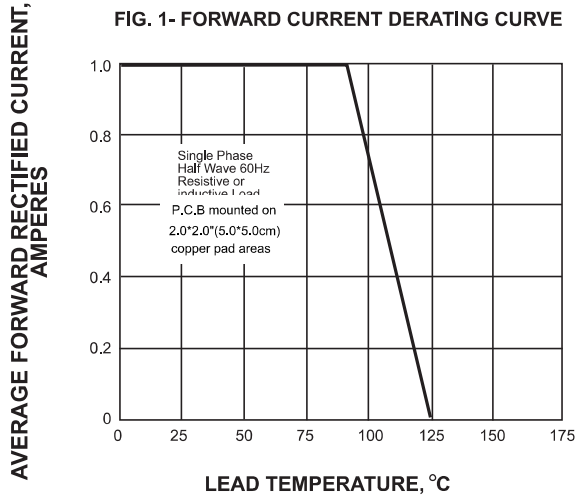


### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)



PARAMETER	SYMBOLS	SL02-GS08	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	30	V
Maximum RMS voltage	$V_{RMS}$	21	V
Maximum DC blocking voltage	$V_{DC}$	30	V
Maximum average forward rectified current at $T_L$ (see fig.1)	$I_{(AV)}$	1.1	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	40.0	A
Maximum instantaneous forward voltage at 1.0A	$V_F$	0.38	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	0.2 10.0	mA
Typical junction capacitance (NOTE 1)	$C_J$	110	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	92	$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +125	$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150	$^\circ\text{C}$

**Note:**1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

### Rating and characteristic curves



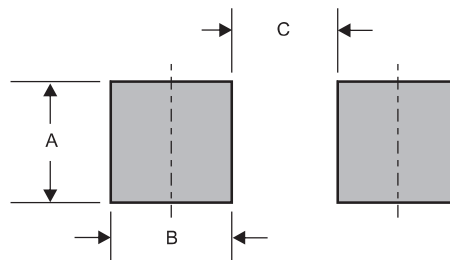
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
SL02-GS08	L3LF

## Suggested solder pad layout

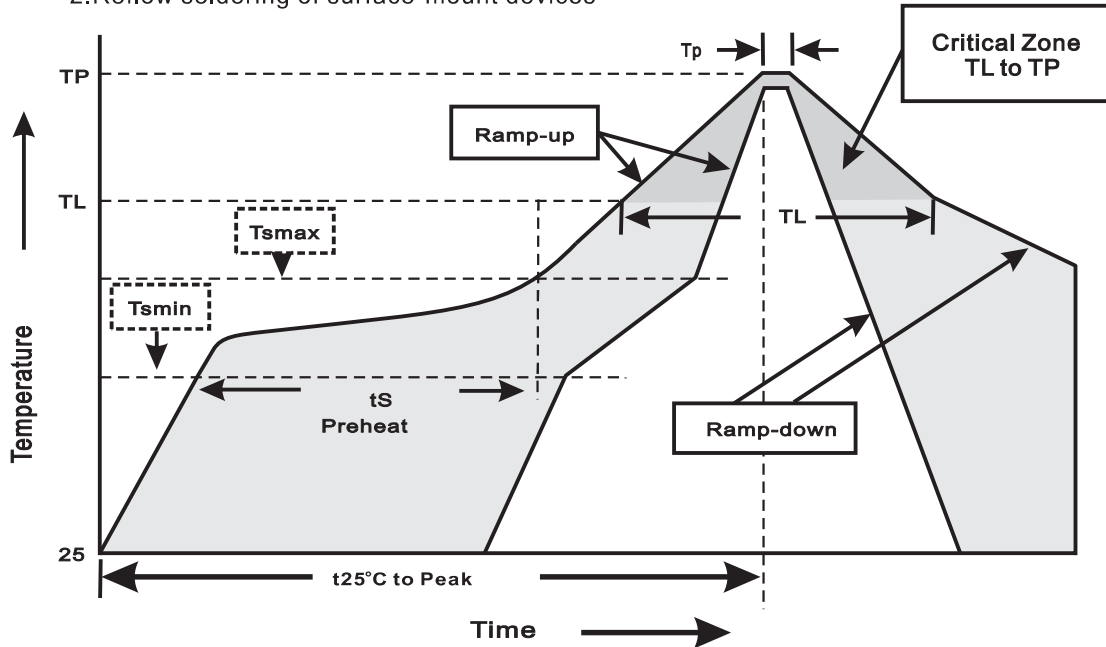


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)

**Suggested thermal profiles for soldering processes**

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes